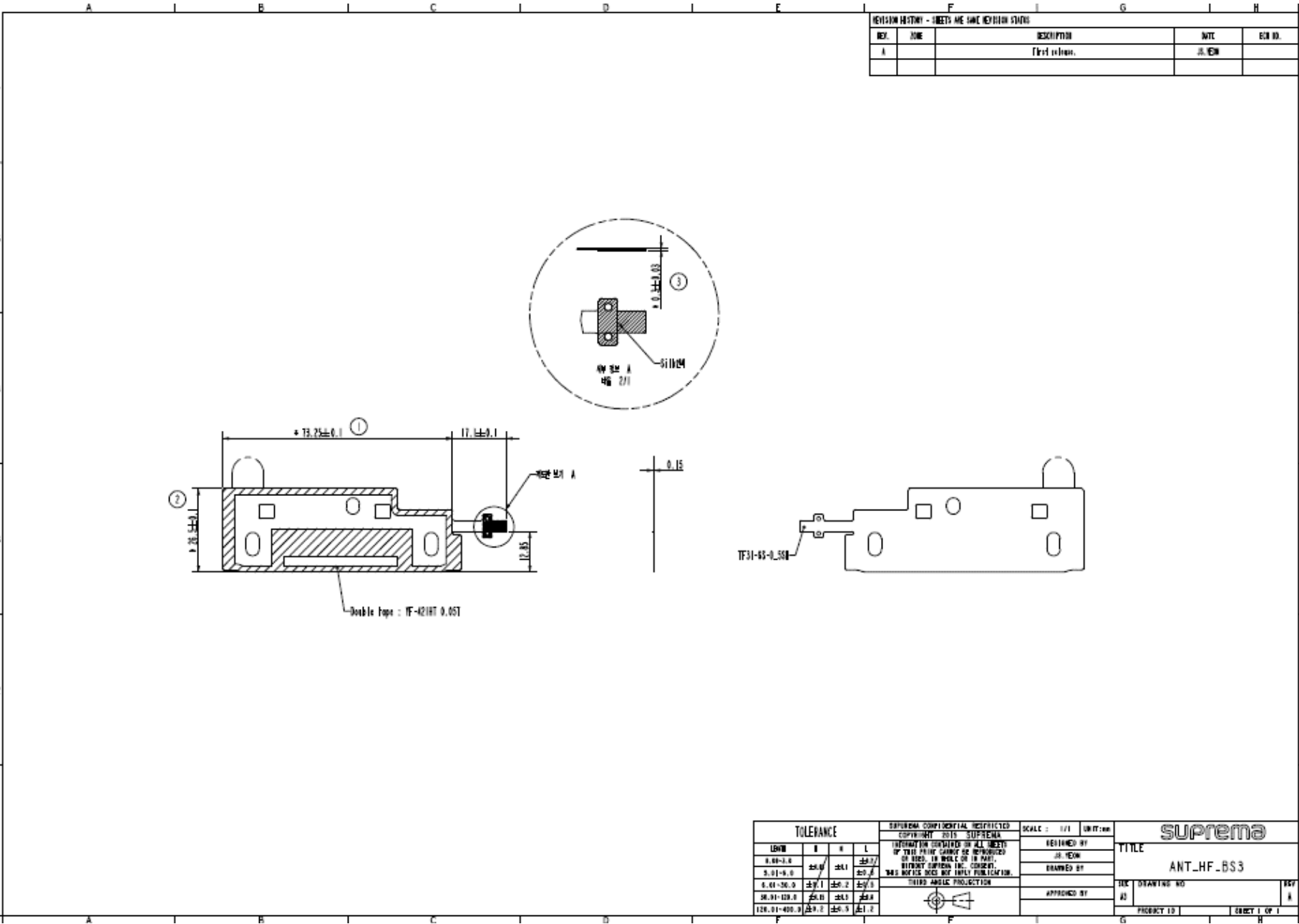


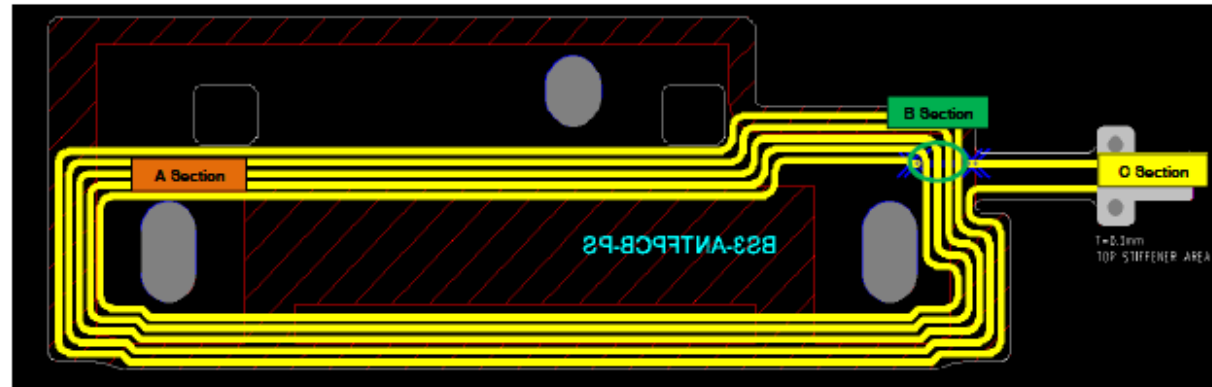
drawing



Dimension

F.P.C STRUCTURE (FPCB구조)

Model	BS3 HF_ANT_PS	Layer	DS
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Layer	Item	Specification	A Section	B Section	C Section		품명	업체명
XXX	PAPER	PAPER		125.0			CP양PE양SC_OS1207 (WHITE)	오성
XXX	TAPE	Adhesive		50.0			4972 (0.05T)	TESA
XXX	Kapton	Polyimide			125.0		5MIL (ADH 40um)	HANWHA
		Adhesive			40.0		HGCS-C850L	
	Coverlay	Polyimide	12.5	12.5	12.5		1/2MIL (ADH 25um)	HANWHA
		Adhesive	25.0	25.0	25.0		HGCS-A505L(Y)	
C/S	Cu Plate	Cu Plate		10.0			Cu Plate	Cu Plate
		Copper foil		36.0				
		Adhesive	15.0	15.0	15.0			
XXX	FCCL	Polyimide	25.0	25.0	25.0		1MIL 10Z ED 3L 양면 HGSL-D211EY	HANWHA
		Adhesive	15.0	15.0	15.0			
		Copper foil	36.0	36.0	36.0			
S/S	Cu Plate	Cu Plate	10.0	10.0	10.0		Cu Plate	Cu Plate
		Adhesive	25.0	25.0			1/2MIL (ADH 25um)	
	Coverlay	Polyimide	12.5	12.5			HGCS-A505L(Y)	HANWHA
LAYER			1	2	1		SCM-500W(WHITE)	서울화학
Total Thickness			176.00	272.00	303.50		무전해 금도금	표면처리
Tolerance					0.3T±0.03		Ni 3-7um, Au: MIN 0.03um	

※ PAPER 두께 제외